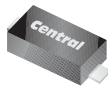


Material Composition Specification

SOD-723 Case



Device average mass **0.8098 mg**
 Fluctuation margin **+/-10%**

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(mg)			(%wt)	(mg)	(ppm)
active device	doped Si	5.24%	0.0424	Si	7440-21-3	5.24%	0.0424	52,358
bond wire	gold or copper	2.64%	0.0214	Au	7440-57-5	2.64%	0.0214	26,426
				Cu	7440-50-8			
leadframe	alloy 42	25.81%	0.209	Ni	7440-02-0	10.84%	0.0878	108,421
				Fe	7439-89-6	14.97%	0.121	149,666
encapsulation*	EMC GREEN	66.31%	0.537	silica (fused)	60676-86-0	51.12%	0.414	511,234
				epoxy resin	29690-82-2	6.67%	0.054	66,683
				phenol resin	9003-35-4	6.42%	0.052	64,213
				carbon black	1333-86-4	0.25%	0.002	2,470
				metal hydroxide	1309-42-8	1.85%	0.015	18,523
plating	100% matte tin	0.001%	.000005	Sn	7440-31-5	0.001%	.000005	6

*EMC GREEN molding compound is Halogen-Free.

Disclaimer

The information provided in this Material Composition data sheet is, to the best of our knowledge, correct. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company.

R0 (7-November 2011)